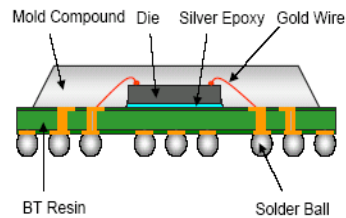


Material Declaration

Compliance Date: Jun/22/2026

RoHS Compliance: Yes

MSL: 3

Pin count /Package		48B BGA (8X10) (Stacked)							
Model (Part) Number		AS6C6416-55BIN							
Package Weight (mg)		180.140							
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part
Chip	Wafer Circuit	18.67	10.36	103,642	Silicon (Si)	7440-21-3	18.670	10.364%	100.00%
Bonding Wire	Conductivity	0.28	0.16	1,554	Gold (Au)	7440-57-5	0.280	0.155%	100.00%
Die Attach 1	Conductivity	2.83	1.57	15,710	Acrylic resin (Die attach film)	(Trade secret)	0.708	0.393%	25.00%
					Silica, amorphous (Die attach film)	7631-86-9	0.637	0.353%	22.50%
					Phenol resin (Die attach film)	(Trade secret)	0.071	0.039%	2.50%
					Polypropylene copolymer (Dicing Tape)	(Trade secret)	0.778	0.432%	27.50%
					Acrylic resin (Dicing Tape)	(Trade secret)	0.425	0.236%	15.00%
					Polyethylene copolymer (Dicing Tape)	(Trade secret)	0.212	0.118%	7.50%
Die Attach 2	Conductivity	1.8	1.00	9,992	Synthetic rubber	(Trade secret)	0.180	0.100%	10.00%
					Silicon, amorphous	7631-86-9	0.360	0.200%	20.00%
					Phenol resin	(Trade secret)	0.180	0.100%	10.00%
					Epoxy resin	(Trade secret)	0.180	0.100%	10.00%
					Polypropylene copolymer (Dicing tape)	(Trade secret)	0.495	0.275%	27.50%
					Acrylic resin	(Trade secret)	0.270	0.150%	15.00%
Substrate	Base Metal	56	31.09	310,869	Barium Sulfate	7727-43-7	0.006	0.003%	0.01%
					Plastics EP	Not Specified	0.006	0.003%	0.01%
					Talc	14807-96-6	0.409	0.227%	0.73%
					Natural Ingredient,not to declare	Trade secret	0.409	0.227%	0.73%
					Additives,not to declare	Trade secret	0.409	0.227%	0.73%
					Silicon dioxide	7631-86-9	0.409	0.227%	0.73%
					Pigment portion,not to declare	Trade secret	0.056	0.031%	0.10%
					Thermosetting resin(including inorganic	Trade Secret	14.610	8.111%	26.09%
					Glass cloth	65997-17-3	14.610	8.111%	26.09%
					Plastics PAK	Not Specified	2.722	1.511%	4.86%
					Cu Plating	7440-50-8	21.840	12.124%	39.00%
					Ni Plating	7440-02-0	0.465	0.258%	0.83%
					Au Plating	1310-73-2	0.050	0.028%	0.09%
Molding Compound	Chip Protection	93.66	51.99	519,929	Silica (Fused)	60676-86-0	83.826	46.534%	89.50%
					Epoxy resin	(Trade secret)	4.683	2.600%	5.00%
					Phenol resin	(Trade secret)	4.683	2.600%	5.00%
					Carbon Black	1333-86-4	0.468	0.260%	0.50%
Solder Ball	Solder	6.900	3.83	38,304	Tin (Sn)	7440-31-5	6.659	3.696%	96.50%
					Silver (Ag)	7440-22-4	0.207	0.115%	3.00%
					Copper (Cu)	7440-50-8	0.035	0.019%	0.50%